

LTC1385

3.3V Low Power EIA/TIA-562 Transceiver

FEATURES

- Operates from a Single 3.3V Supply
- Low Supply Current: I_{CC} = 200µA
- $I_{CC} = 35\mu A$ in Driver Disable Mode
- **I**_{CC} = 0.2 μ A in Shutdown Mode
- ESD Protection Over ±10kV
- Uses Small Capacitors: 0.1µF
- Operates to 120kBaud
- Output Overvoltage Does Not Force Current Back into Supplies
- EIA/TIA-562 I/O Lines Can Be Forced to ±25V Without Damage
- Pin Compatible with LT1180A

APPLICATIONS

- Notebook Computers
- Palmtop Computers

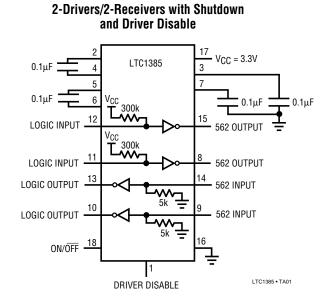
DESCRIPTION

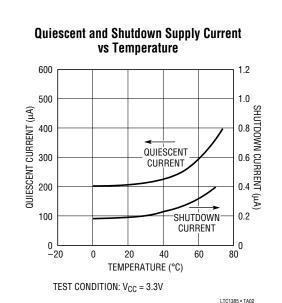
The LTC1385 is an ultra-low power, 2-driver/2-receiver EIA/TIA-562 transceiver which operates from a single 3.3V supply. The charge pump requires only four space-saving 0.1μ F capacitors.

The transceiver operates in one of three modes: Normal, Driver Disable or Shutdown. In the Normal mode, I_{CC} is only 200µA in the unloaded condition. In the Driver Disable mode, the charge pump is turned off, the driver outputs are forced into three-state, both receivers are kept active, and I_{CC} drops to 35µA. In the Shutdown mode, everything is turned off and I_{CC} drops to 0.2µA.

The LTC1385 is fully compliant with all data rate and overvoltage EIA/TIA-562 specifications. The transceiver can operate up to 120kbaud with a 1000pF, $3k\Omega$ load. Both driver outputs and receiver inputs can be forced to $\pm 25V$ without damage, and can survive multiple $\pm 10kV$ ESD strikes.

TYPICAL APPLICATION





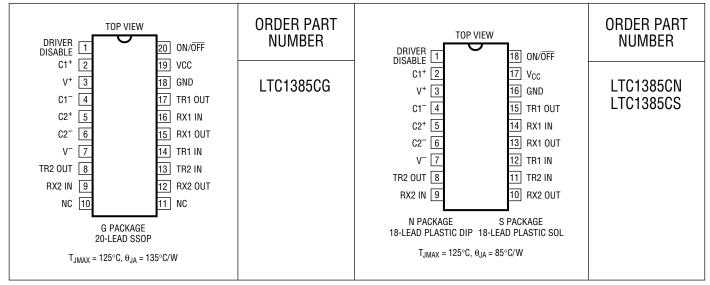


ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V _{CC})	5V
Input Voltage	
Driver	$-0.3V$ to V _{CC} + 0.3V
Receiver	25V to 25V
Digital Input	$-0.3V$ to V _{CC} + 0.3V
Output Voltage	
Driver	– 25V to 25V
Receiver	$-0.3V$ to V _{CC} + 0.3V

Short-Circuit Duration	
V ⁺	30 sec
V ⁻	30 sec
Driver Output	Indefinite
Receiver Output	Indefinite
Operating Temperature Range	0°C to 70°C
Storage Temperature Range	-65°C to 150°C
Lead Temperature (Soldering, 10 sec)	300°C

PACKAGE/ORDER INFORMATION



Consult factory for Industrial and Military grade parts.

DC ELECTRICAL CHARACTERISTICS

 V_{CC} = 3.3V, C1 = C2 = C3 = C4 = 0.1 μ F, $V_{ON/OFF}$ = V_{CC} , Driver Disable = V_{CC} , unless otherwise noted.

PARAMETER	CONDITIONS			MIN	ТҮР	MAX	UNITS
Any Driver	·						
Output Voltage Swing		ositive legative	•	3.7 -3.7	4.5 - 4.5		V V
Logic Input Voltage Level	Input Low Level (V _{OUT} = High) Input High Level (V _{OUT} = Low)		•	2.0	1.4 1.4	0.8	V V
Logic Input Current	$V_{IN} = V_{CC}$ $V_{IN} = 0V$		•		-20	5 -40	μΑ μΑ
Output Short-Circuit Current	V _{OUT} = 0V				±10		mA
Output Leakage Current	Shutdown or Driver Disable or $V_{CC} = 0V$ (No $V_{OUT} = \pm 20V$	te 3,4),	•		±10	±500	μA



DC ELECTRICAL CHARACTERISTICS

 V_{CC} = 3.3V, C1 = C2 = C3 = C4 = 0.1 μ F, $V_{ON/OFF}$ = V_{CC} , Driver Disable = V_{CC} , unless otherwise noted.

PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
Any Receiver	I					
Input Voltage Thresholds	Input Low Threshold		0.8	1.3		V
	Input High Threshold	•		1.7	2.4	V
Hysteresis		•	0.1	0.4	1.0	V
Input Resistance	$-10V \le V_{IN} \le 10V$		3	5	7	kΩ
Output Voltage	Output Low, $I_{OUT} = -1.6mA$ (V _{CC} = 3.3V)	•		0.2	0.4	V
	Output High, $I_{OUT} = 160\mu A (V_{CC} = 3.3V)$	•	3.0	3.2		V
Output Short-Circuit Current	Sinking Current, V _{OUT} = V _{CC}		-5	-20		mA
•	Sourcing Current, V _{OUT} = 0V		2	7		mA
Output Leakage Current	Shutdown (Note 4), $0V \le V_{OUT} \le V_{CC}$	•		1	10	μA
Power Supply Generator						
V ⁺ Output Voltage	I _{OUT} = 0mA			5.7		V
	I _{OUT} = 5mA			5.5		V
V ⁻ Output Voltage	I _{OUT} = 0mA			-5.3		V
	$I_{OUT} = -5mA$			-5.0		V
Supply Rise Time	Shutdown or Driver Disable to Turn-On			0.2		ms
Power Supply						
V _{CC} Supply Current	No Load (Note 2)			0.2	0.5	mA
Supply Leakage Current (V _{CC})	Shutdown (Note 4)			0.2	10	μA
	Driver Disable (Note 3)	•		35	50	μA
Digital Input Threshold Low		•		1.4	0.8	V
Digital Input Threshold High			2.0	1.4		V

AC CHARACTERISTICS $V_{CC} = 3.3V$, $C1 = C2 = C3 = C4 = 0.1 \mu F$, unless otherwise noted.

PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
Slew Rate	R _L = 3k, C _L = 51pF			8	30	V/µs
	$R_{L} = 3k, C_{L} = 1000pF$		3	5		V/µs
Driver Propagation Delay	t _{HLD} (Figure 1)	•		2	3.5	μs
(TTL to EIA/TIA-562)	t _{LHD} (Figure 1)	•		2	3.5	μs
Receiver Propagation Delay	t _{HLR} (Figure 2)	•		0.3	0.8	μs
(EIA/TIA-562 to TTL)	t _{LHR} (Figure 2)	•		0.2	0.8	μs

The \bullet denotes specifications which apply over the operating temperature range 0°C \leq T_A \leq 70°C.

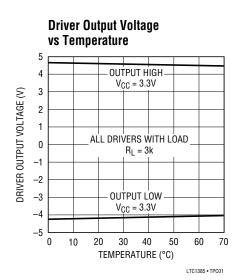
Note 1: Absolute maximum ratings are those values beyond which the life of the device may be impaired.

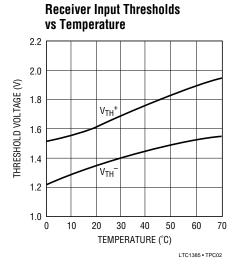
Note 2: Supply current is measured with driver and receiver outputs unloaded.

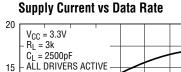
Note 3: Measurements made in the Driver Disable mode are performed with $V_{DRIVER DISABLE}$ = GND and $V_{ON/\overline{OFF}}$ = V_{CC} .

Note 4: Measurements made in the Shutdown mode are performed with $V_{ON/\overline{OFF}}$ = 0V.

TYPICAL PERFORMANCE CHARACTERISTICS







SUPPLY CURRENT (mA)

10

5

0

18

16

14

12

10

8

6

4

2

0

0 10

SHORT-CIRCUIT CURRENT (mA)

0 20 40 60 80 100

LTC1385 • TPC03

50

70

60

LTC1385 • TPC06

DATA RATE (kBAUD)

Driver Short-Circuit Current

I_{SC}

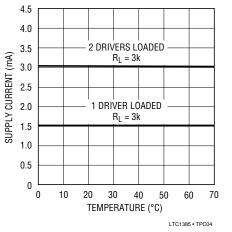
I_{SC}⁺

20 30 40

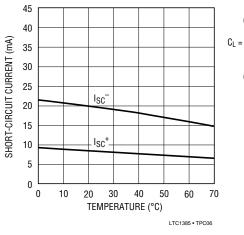
vs Temperature

120 140

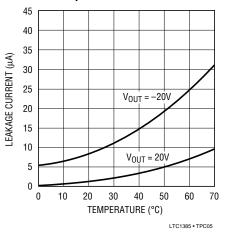
V_{CC} Supply Current vs Temperature



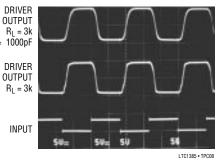




Driver Leakage in Shutdown vs Temperature

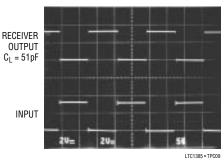


Driver Output Waveforms



Receiver Output Waveform

TEMPERATURE (°C)





PIN FUNCTIONS

 V_{CC} : 3.3V Input Supply Pin. This pin should be decoupled with a 0.1 μF ceramic capacitor.

GND: Ground Pin.

ON/OFF: TTL/CMOS Compatible Shutdown Pin. A logic low puts the device in the Shutdown mode independent of the Driver Disable pin. The supply current drops to 0.2μ A and all driver and receiver outputs are forced into three-state.

DRIVER DISABLE: TTL/CMOS Compatible Input Pin. With the ON/ \overline{OFF} pin held high, a logic low forces the part into the Driver Disable mode with the charge pump turned off and the driver outputs forced into three-state. Both receivers remain active and the supply current drops to 35µA. A logic high forces the part into the Normal mode.

V⁺: Positive Supply Output (EIA/TIA-562 Drivers). $V^+ \cong 2V_{CC} - 1V$. This pin requires an external capacitor $C = 0.1 \mu F$ for charge storage. The capacitor may be tied to ground or V_{CC}. With multiple devices, the V⁺ and V⁻ pins may share a common capacitor. For a large number of devices, increasing the size of the shared common storage capacitors is recommended to reduce ripple.

V⁻: Negative Supply Output (EIA/TIA-562 Drivers). V⁻ $\cong -(2V_{CC} - 1.3V)$. This pin requires an external capacitor C = 0.1µF for charge storage. **C1⁺, C1⁻, C2⁺, C2⁻:** Commutating Capacitor Inputs. These pins require two external capacitors $C = 0.1 \mu$ F: one from C1⁺ to C1⁻, and another from C2⁺ to C2⁻. To maintain charge pump efficiency, the capacitor's effective series resistance should be less than 2 Ω .

TR IN: EIA/TIA-562 Driver Input Pins. Inputs are TTL/ CMOS compatible. The inputs of unused drivers can be left unconnected since 300k input pull-up resistors to V_{CC} are included on chip. To minimize power consumption, the internal driver pull-up resistors are disconnected from V_{CC} in the Shutdown mode.

TR OUT: Driver Outputs at EIA/TIA-562 Voltage Levels. Outputs are in a high impedance state when in the Shutdown or Driver Disable mode or $V_{CC} = 0V$. The driver outputs are protected against ESD to $\pm 10kV$ for human body model discharges.

RX IN: Receiver Inputs. These pins can be forced to $\pm 25V$ without damage. The receiver inputs are protected against ESD to $\pm 10kV$ for human body model discharges. Each receiver provides 0.4V of hysteresis for noise immunity.

RX OUT: Receiver Outputs with TTL/CMOS Voltage Levels. Outputs are in a high impedance state when in the Shutdown mode.

SWITCHING TIME WAVEFORMS

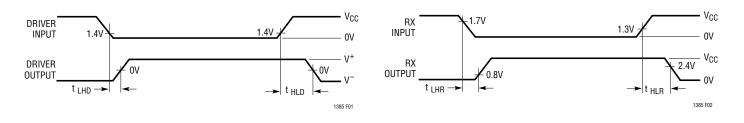


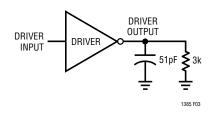
Figure 1. Driver Propagation Delay Timing

Figure 2. Receiver Propagation Delay Timing

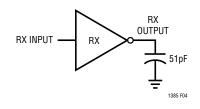


TEST CIRCUITS

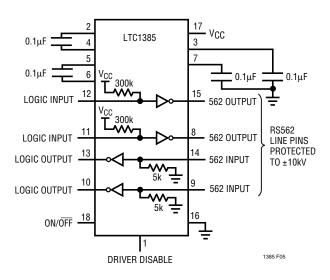
Driver Timing Test Load



Receiver Timing Test Load



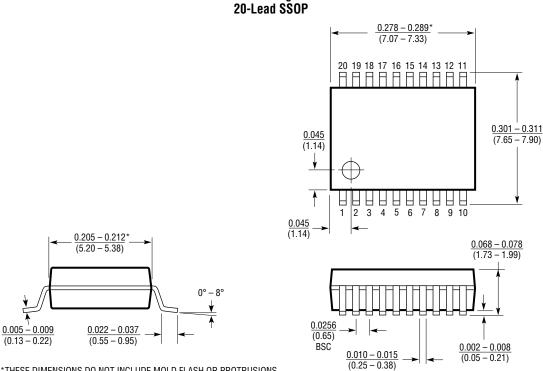
ESD Test Circuit





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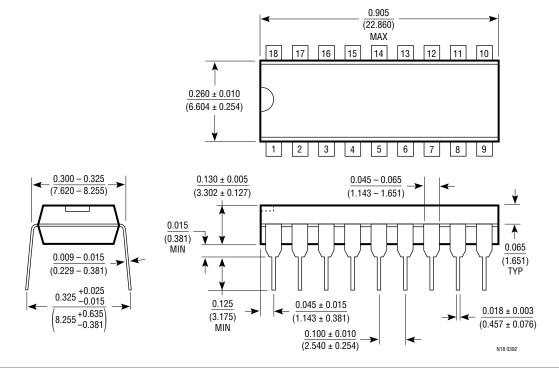
PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.



G Package

*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 INCH (0.15mm).

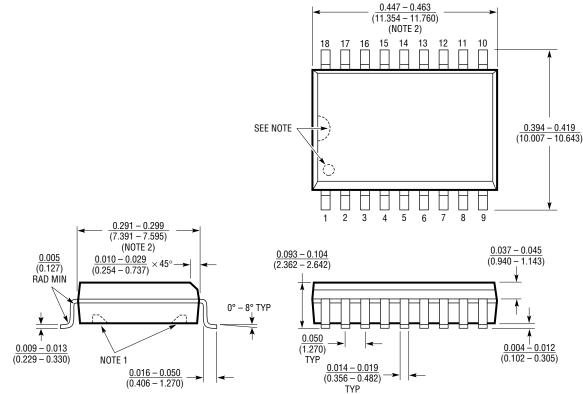
> N Package 18-Lead Plastic DIP



TECHNOLOGY

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PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.



S Package 18-Lead Plastic SOL

NOTE:

1. PIN 1 IDENT, NOTCH ON TOP AND CAVITIES ON THE BOTTOM OF PACKAGES ARE THE MANUFACTURING OPTIONS. THE PART MAY BE SUPPLIED WITH OR WITHOUT ANY OF THE OPTIONS.

2. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

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